

ACTS240MS

High Reliability, Radiation Hardened Octal Buffer/Line Driver, Three-State

Rev X.00 Jan 13, 2017

Features

- Devices QML Qualified in Accordance with MIL-PRF-38535
- · Detailed Electrical and Screening Requirements are Contained in SMD# 5962-96717 and Intersil's QM Plan
- 1.25 Micron Radiation Hardened SOS CMOS
- Total Dose >300K RAD (Si)
- Single Event Upset (SEU) Immunity: <1 x 10⁻¹⁰ Errors/ Bit/Day (Typ)
- SEU LET Threshold>100 MEV-cm²/mg
- Dose Rate Upset>10¹¹ RAD (Si)/s, 20ns Pulse
- Dose Rate Survivability>10¹² RAD (Si)/s, 20ns Pulse
- · Latch-Up Free Under Any Conditions
- Military Temperature Range-55°C to +125°C
- · Significant Power Reduction Compared to ALSTTL Logic
- DC Operating Voltage Range 4.5V to 5.5V
- · Input Logic Levels
 - VIL = 0.8V Max
 - VIH = VCC/2 Min
- Input Current $\leq 1\mu A$ at VOL, VOH
- Fast Propagation Delay17.5ns (Max), 12ns (Typ)

Description

The Intersil ACTS240MS is a Radiation Hardened High Reliability, High-Speed CMOS/SOS having two active low enable inputs.

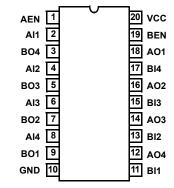
The ACTS240MS utilizes advanced CMOS/SOS technology to achieve high-speed operation. This device is a member of a radiation hardened, high-speed, CMOS/SOS Logic Family.

The ACTS240MS is supplied in a 20 lead Ceramic Flatpack (K suffix) or a Dual-In-Line Ceramic Package (D suffix).

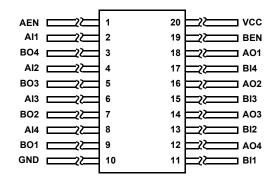
Pinouts

20 PIN CERAMIC DUAL-IN-LINE MIL-STD-1835 DESIGNATOR CDIP2-T20, **LEAD FINISH C**

TOP VIEW



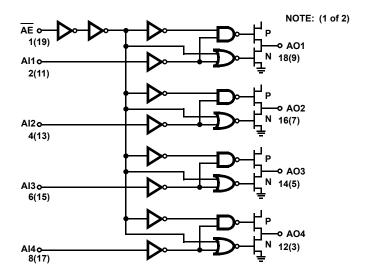
20 PIN CERAMIC FLATPACK MIL-STD-1835 DESIGNATOR CDFP4-F20, **LEAD FINISH C** TOP VIEW



Ordering Information

PART NUMBER	TEMPERATURE RANGE	SCREENING LEVEL	PACKAGE
5962F9671701VRC	-55°C to +125°C	MIL-PRF-38535 Class V	20 Lead SBDIP
5962F9671701VXC	-55°C to +125°C	MIL-PRF-38535 Class V	20 Lead Ceramic Flatpack
ACTS240D/Sample	25°C	Sample	20 Lead SBDIP
ACTS240K/Sample	25°C	Sample	20 Lead Ceramic Flatpack
ACTS240HMSR	25°C	Die	Die

Functional Diagram



TRUTH TABLE

INP	OUTPUT	
AE, BE	Aln, Bln	AOn, BOn
L	L	Н
L	Н	L
Н	Х	Z

NOTE: H = High Voltage Level, L = Low Voltage Level, X = Immaterial, Z = High Impedance

Die Characteristics

DIE DIMENSIONS:

100 mils x 100 mils 2.54mm x 2.54mm

METALLIZATION:

Type: AlSi

Metal 1 Thickness: 7.125kÅ ±1.125kÅ

Metal 2 Thickness: 9kÅ ±1kÅ

GLASSIVATION:

Type: SiO₂

Thickness: 8kÅ ±1kÅ

WORST CASE CURRENT DENSITY:

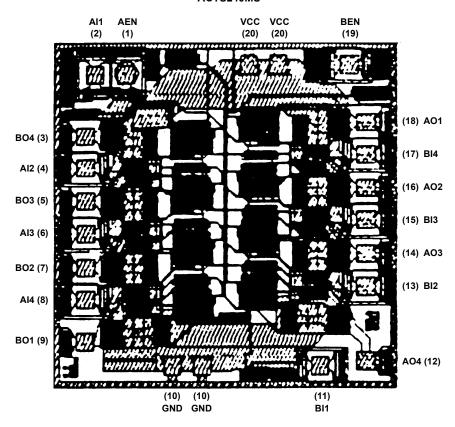
 $< 2.0 \times 10^5 \text{A/cm}^2$

BOND PAD SIZE:

110μm x 110μm 4.4 mils x 4.4 mils

Metallization Mask Layout

ACTS240MS



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